

TMAX-1770-XXX-M M lded P e I d c

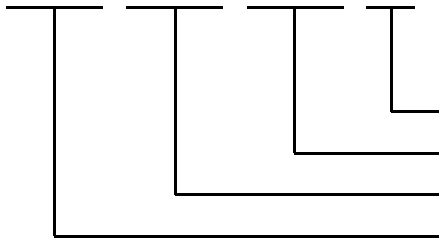
Features

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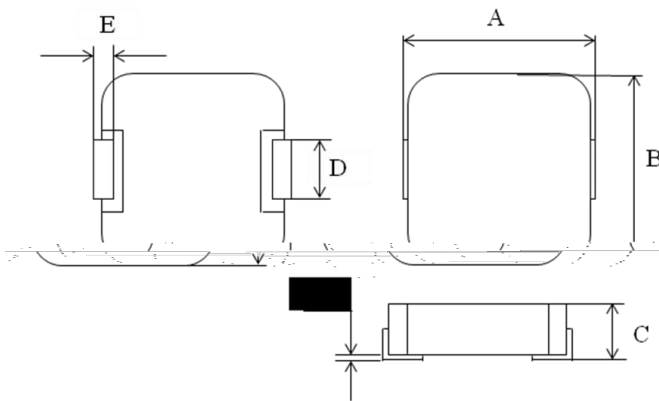
Applications

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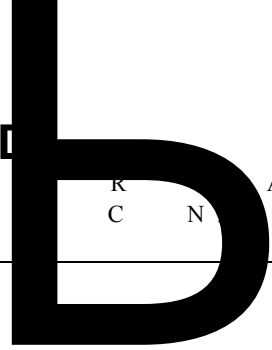
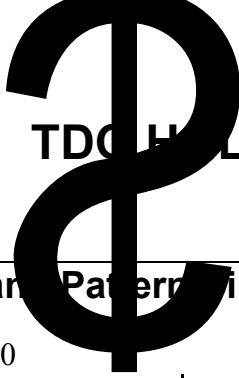
Product Description



Dimensions

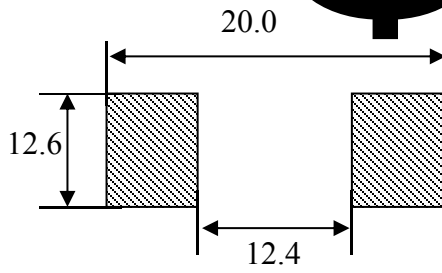


	17.5 Max.
	17.15 Max.
	7.0 Max.
	11.8±0.3
	2.5±0.5
	0~0.30



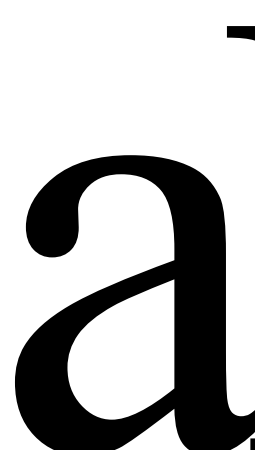
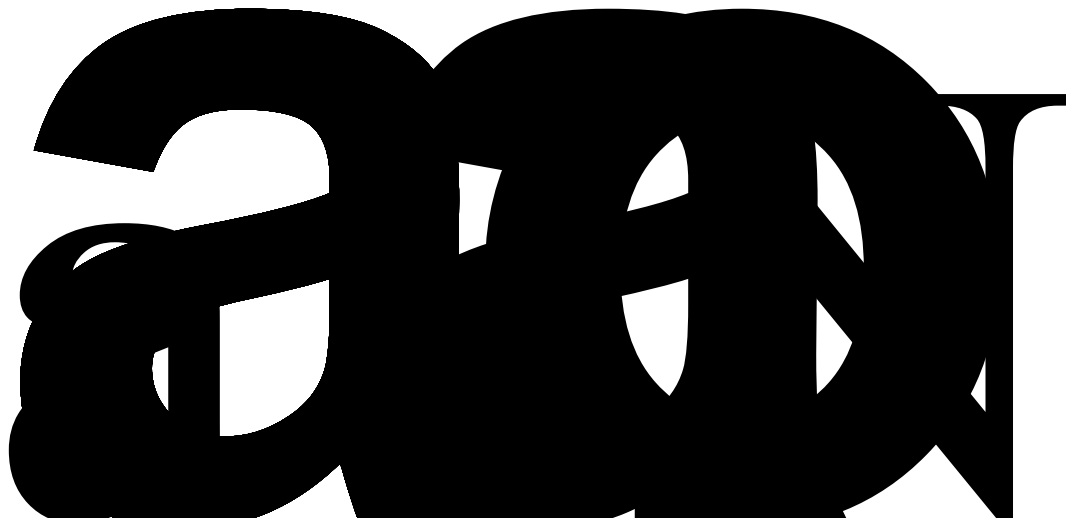
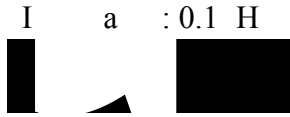
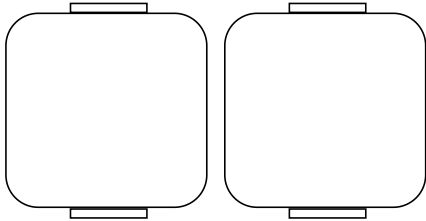
R
C N A0

Recommend Land Pattern Dimensions



Marking

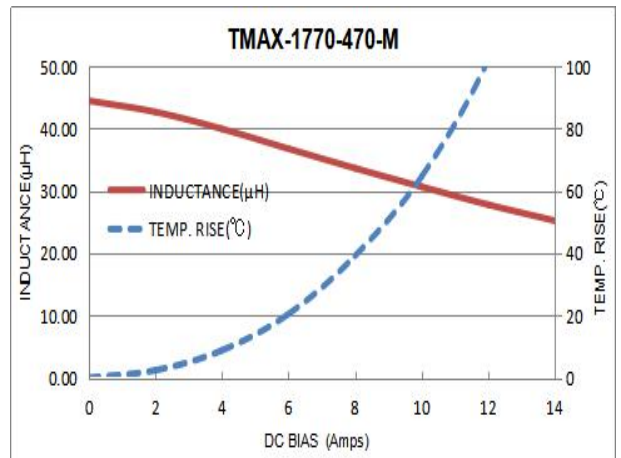
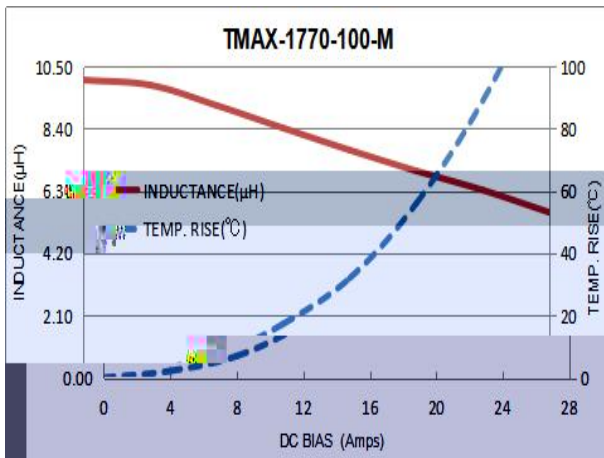
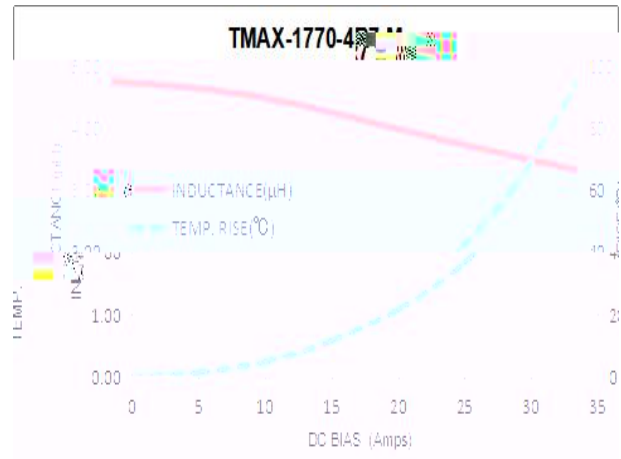
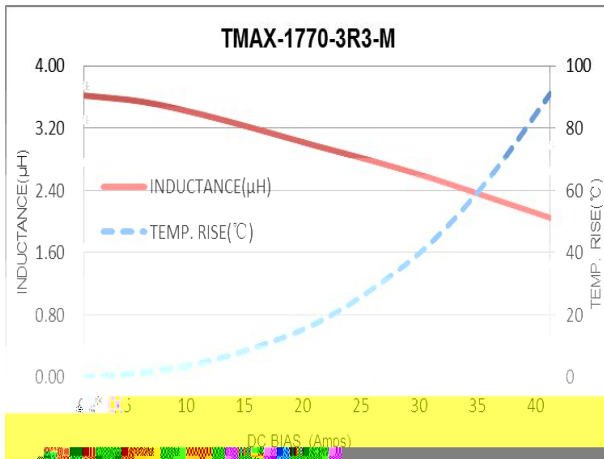
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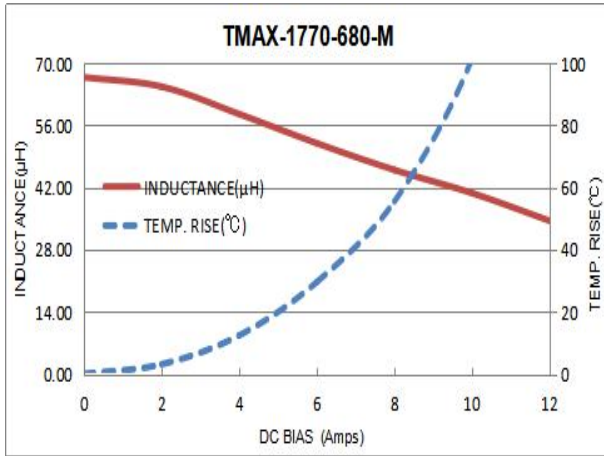


Notes:

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Inductance and Temperature Rise vs. DC Current





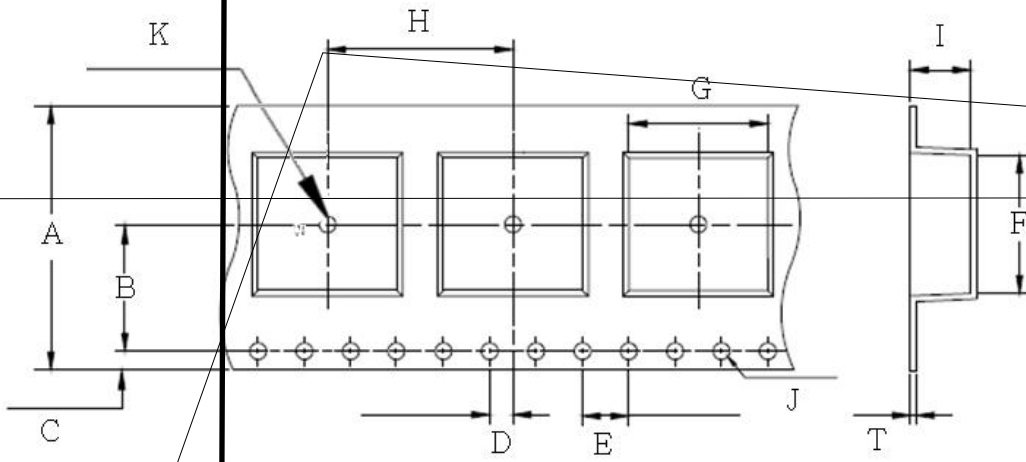
Reliability:

Item	Test Method	Specification and Requirement
	± ± °C ±	
		±

Reliability:

Item	Test Method	Specification and Requirement
	\pm \pm \rightarrow \rightarrow \pm \pm \rightarrow	
	\pm	\pm
	\pm	
	\pm	
	\pm	

Packaging Dimensions



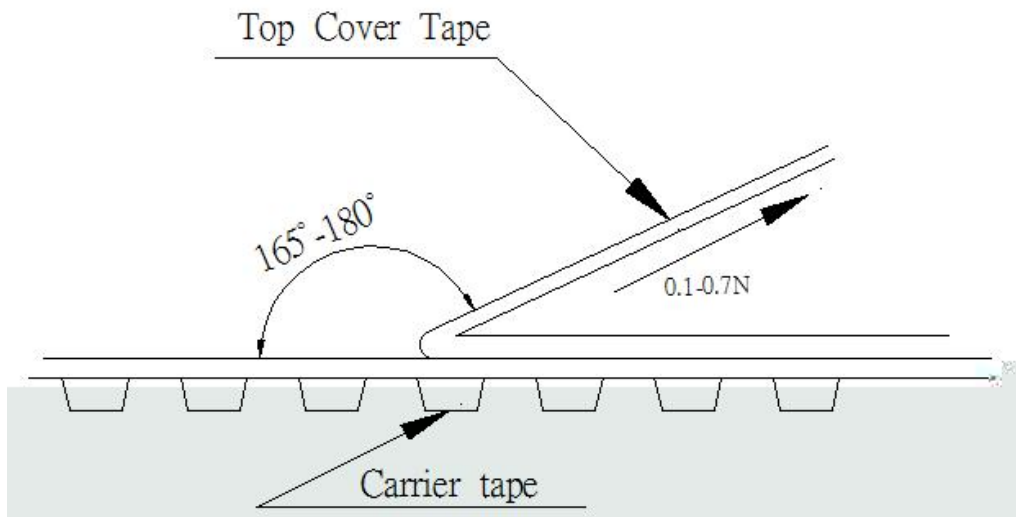
±	±	±	±	±	±
±	±	±	±	±	±



±	±	

Peeling of top cover tape

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Reflow Profile

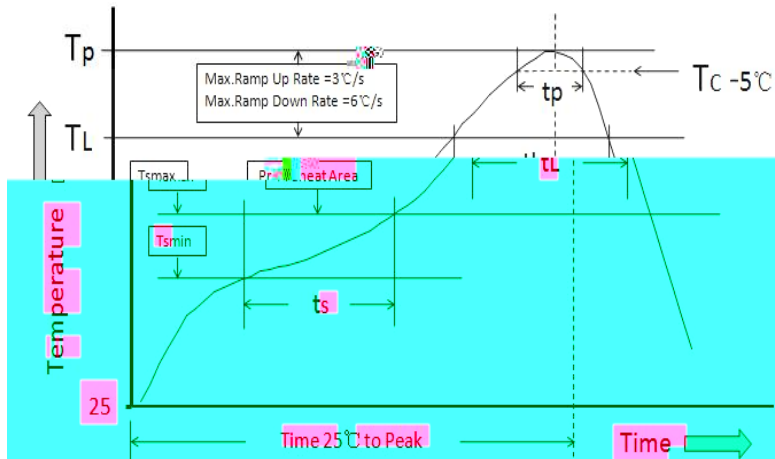


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≧350
<	°C	°C
≧	°C	°C

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<	°C	°C	°C
	°C	°C	°C
	°C	°C	°C

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder
	°C	°C
	°C	°C
	°C	°C
	°C	°C
	°C	°C
°C		
	°C	°C
°C		

Numbers of taping**Label marking****Production Label****Shipping Label****Care note for use****➤ Storage Condition****➤ Use Temperature**

Care note for Safety